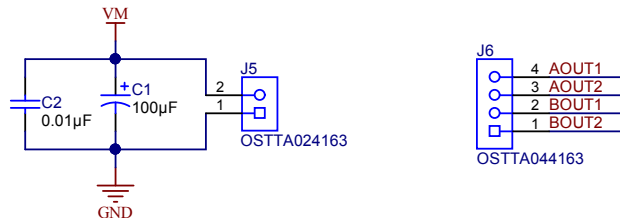
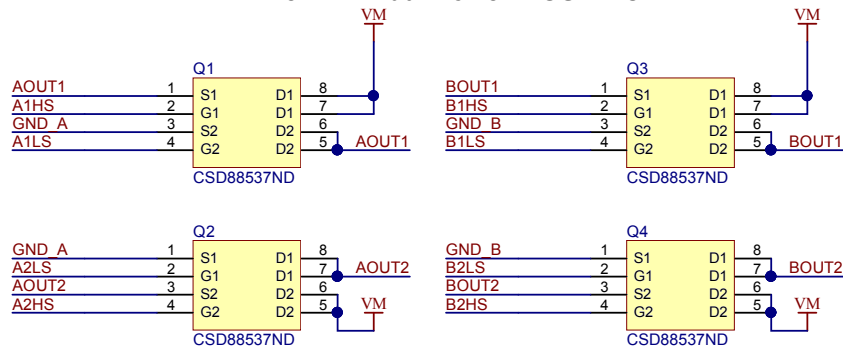


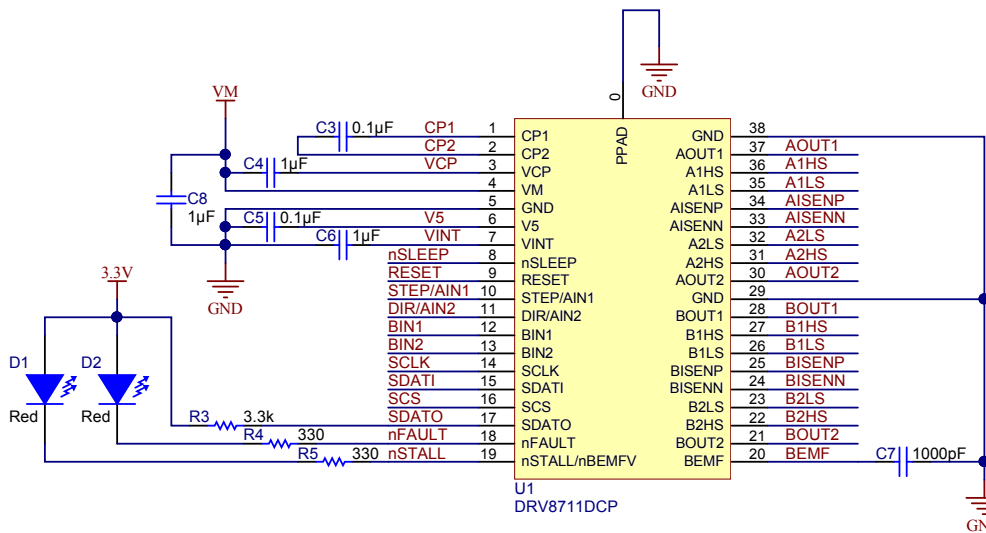
Power/Motor Connections



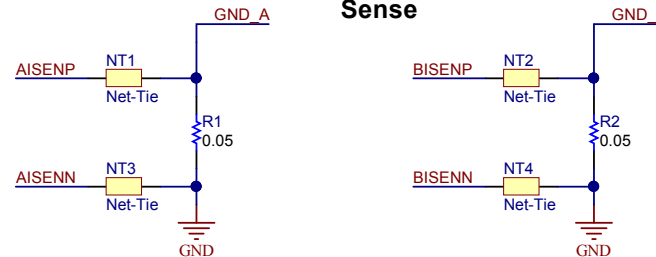
NexFET Dual Power MOSFETs



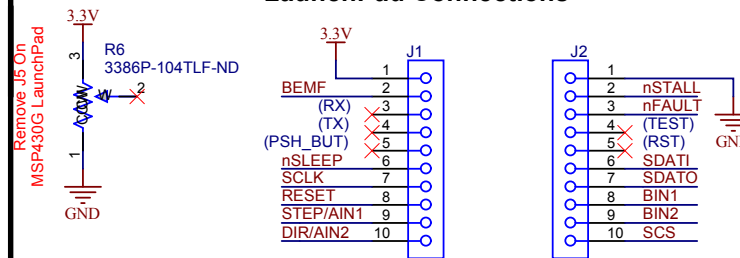
DRV8711



Sense



LaunchPad Connections



PCB Number: TIDA-00740
PCB Rev: A

PCB
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Number: TIDA-00740 | Rev: A
SVN Rev: Version control disabled
Drawn By:
Engineer:

Designed for: Public Release | Mod. Date: 11/2/2015
Project Title: Stepper Motor BoosterPack
Sheet Title:
Assembly Variant: [No Variations] | Sheet: 1 of 1
File: BOOST-DRV8711.SchDoc | Size: A4
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